PMP4484 BOM

Designator	Quantity	Description	Footprint	Value	Part number	MFR
C1, C2	2	CAP, AL, 470 µF, 50 V, +/- 20%, 0.034 ohm, TH	FC_1000x2000	470µF		Panasonic
C3	1	CAP, CERM, 1000 pF, 1000 V, +/- 10%, 1206	1206	1000pF		Murata
C4	1	CAP, Film, 0.1 µF, 305 V, +/- 20%, TH, X-CAP	B32921_1300x1	0.1µF	B32921C3104M	Panasonic
C6	2	CAP, Film, 0.22 µF, 630 V, +/- 10%, TH		0.22µF		Murata
C5	2	CAP, Film, 0.1 µF, 630 V, +/- 10%, TH		0.1µF		Murata
C7	1	Capacitor, Ceramic	0603	1uF/25V		Murata
C10	1	Capacitor, Ceramic	0603	0.1uF/25V		Murata
C11	1	Capacitor, Ceramic	0603	47pF/50V		Murata
C14, C15, C17	3	Capacitor, Ceramic	0603	1000pF/50V		Murata
C28, C29, C32, C33, C36, C37	6	Capacitor, Ceramic	0603	1uF/10V		Murata
C8	1	CAP, AL	FM_500x1100	10µF/63V		Panasonic
C12	1	CAP, AL	FM_500x1100	100µF/16V		Panasonic
C16, C25	2	CAP, AL	FM_500x1100	47µF/25V		Panasonic
C18, C20	2	Capacitor, Ceramic	0805	2.2µF/25V	GRM219R61E225KA12D	Murata
C26, C27, C30, C31, C34, C35	6	Capacitor, Ceramic	0805	2.2uF/50V		Murata
C13	1	Y-cap, 2200pF	0805	2200pF		Murata
C19	1	CAP, CERM, 0.33 µF, 16 V, +/- 10%, X7R, 0603	0603	0.33µF/16V	GRM188R71C334KA01D	Murata
C21, C22	2	CAP, CERM, 22 µF, 6.3 V, +/- 10%, X7R, 1206	1206	22µF/6.3V	GRM31CR70J226KE19L	Murata
C23	1	Capacitor	0603	68nF		Murata
C24	1	CAP, CERM, 1 µF, 100 V, +/- 10%, X7R, 1206	1206	1µF/100V	GRM31CR72A105KA01L	Murata
D2	1	Diode, Ultrafast, 400 V, 5 A, PowerDI5	PowerDI5		PDU540-13	Diodes
D3	1	Diode, P-N, 1000 V, 1 A, TH	DO-41		FR107	Diodes
D4	1	RECT BRIDGE GPP 600V 2A KBP	MICRODIP_4		KBP206G	Fairchild
D5	1	Diode, Ultrafast, 400 V, 1 A, SMA	SMA		MURA140T3G	Onsemi
D6	1	DIODE GEN PURP 200V 200MA SOD323	SOD323		BAS20HT1G	Onsemi
D7	1	Diode, Zener, 15 V, 500 mW, SOD-123	SOD-123		MMSZ4702T1G	Onsemi
D9	1	Diode, P-N, 60 V, 1 A, TH	DO-41		SR106	Diodes
D10	1	Diode, Schottky, 100 V, 1 A, SOD-123FL	SOD-123FL		MBR1H100SFT3G	Onsemi
D11	1	Diode, Switching, 70 V, 0.215 A, SOT-23	SOT-23		BAV199-TP	Micro Commercial
D12, D13, D14, D15, D16, D17	6	Diode, Schottky, 60 V, 1 A, SMA	SMA		B160-13-F	Diodes

F1	1	Square fuse, 1A/300V, size: 8.5mm(L)X4(W)mmX 8mm(H)			3691100000	Littlefuse
J1, J2, J3, J4, J5, J6, J8, J9	8	Header, 100mil, 2x1, Tin, TH			90120-0122	Molex
J7	1	Header, 2.54 mm, 6x1, Gold, TH			61300611121	Wurth
L1	1	Inductor, Wirewound, Ferrite, 1 mH, TH	D8*10	1mH		Wurth
L2	1	Coupled inductor, 510uH, TH		510uH		Wurth
L3	1	Coupled inductor, 10 mH, 0.7 A, 0.35 ohm, TH		10mH		Wurth
L4	1	Inductor, Shielded Drum Core, Metal Composite, 68 µH, 0.22 A, 1.15 ohm, SMD	WE-TPC_3816	68µH	744031680	Wurth
L5, L6	2	Inductor, Unshielded Drum Core, Ferrite, 330 µH	IND_WE-TI_XS	330µH		Wurth
L7, L8	2	Inductor, Unshielded Drum Core, Ferrite, 390 µH	IND_WE-TI_XS	390µH		Wurth
L9, L10	1	Inductor, Unshielded Drum Core, Ferrite, 470 µH	IND_WE-TI_XS	470µH		Wurth
Q2	1	MOSFET, N-CH, 800 V, 6 A, TO-220AB	TO-220AB		SPP06N80C3	infineon
R1, R10	2	Resistor, Chip, 1/8W, 1%	0805	10k	CRCW08051K00FKEA	Yageo
R2, R13	2	Resistor, Chip, 1/8W, 1%	0805	24k		Yageo
R5, R8, R14	3	Resistor, Chip, 1/8W, 1%	0805	680k		Yageo
R6, R9, R15	3	Resistor, Chip, 1/8W, 1%	0805	100k		Yageo
R11, R19	2	Resistor, Chip, 1/8W, 1%	0805	10		Yageo
R18	1	Resistor, Chip, 1/8W, 1%	0805	3.3k		Yageo
R3, R4	2	Resistor, Chip, 1/4W, 1%	1206	150k		Yageo
R7	1	Resistor, Chip, 1/4W, 1%	1206	75		Yageo
R23, R24	2	Resistor, Chip, 1/4W, 1%	1206	1		Yageo
R17	1	Resistor, Chip, 1/10W, 1%	0603	180k		Yageo
R20	1	Resistor, Chip, 1/10W, 1%	0603	330		Yageo
R22, R28, R32, R62	4	Resistor, Chip, 1/10W, 1%	0603	10k		Yageo
R25	1	Resistor, Chip, 1/10W, 1%	0603	4.3k		Yageo
R26	1	Resistor, Chip, 1/10W, 1%	0603	36k		Yageo
R33	1	Resistor, Chip, 1/10W, 1%	0603	3k		Yageo
R34, R30	2	Resistor, Chip, 1/10W, 1%	0603	2.4k		Yageo
R35, R38, R41, R42, R47, R48	6	Resistor, Chip, 1/10W, 1%	0603	40.2k		Yageo
R37, R40	2	Resistor, Chip, 1/10W, 1%	0603	24k		Yageo
R36, R39	2	Resistor, Chip, 1/10W, 1%	0603	360k		Yageo
R43, R46	2	Resistor, Chip, 1/10W, 1%	0603	22k		Yageo

R44, R45	2	Resistor, Chip, 1/10W, 1%	0603	300k		Yageo
R50, R51	2	Resistor, Chip, 1/10W, 1%	0603	30k		Yageo
R49, R52	2	Resistor, Chip, 1/10W, 1%	0603	220k		Yageo
R16	1	Resistor, Chip, 1/10W, 1%	0603	22k		Yageo
R27	1	Resistor, Chip, 1/10W, 1%	0603	1k		Yageo
R29, R31	0	Resistor, Chip, 1/10W, 1%	0603	na		Yageo
R21	3	Resistor, Chip, 1/10W, 1%	0603	20k		Yageo
RV1	1	Varistor (Voltage-Sensitive Resistor)			07D471K	Bourns
T1	1	Auxiliary Flyback Transformer				Haoyang
U1	1	LED Lighting Power Controller, 8-pin SOIC, Green			UCC28810D	TI
U2	1	Opto-Isolator, 1 Channel, SMT			LTV-817S	Lite-On
U3	1	Wide Input Voltage Range Buck Regulator with High Efficiency Sleep Mode			LMR16006XDDC	TI
U4	1	PRECISION PROGRAMMABLE REFERENCE, DBZ0003A	SOT-23		TL431AIDBZ	TI
U5, U6, U7, U8, U9, U10	6	1A 60W Common Anode Capable Constant Current Buck LED Driver			LM3414HVMR/NOPB	TI

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